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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	17
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1828-e-so

TABLE 1-3: PIC16(L)F1828 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RC3/AN7/CPS7/C12IN3-/ P2A(1,2)/CCP2(1,2)/P1C(1,2)/ MDMIN	RC3	TTL	CMOS	General purpose I/O.
	AN7	AN	—	A/D Channel 7 input.
	CPS7	AN	—	Capacitive sensing input 7.
	C12IN3-	AN	—	Comparator C1 or C2 negative input.
	P2A	—	CMOS	PWM output.
	CCP2	AN	—	Capture/Compare/PWM2.
	P1C	—	CMOS	PWM output.
	MDMIN	—	CMOS	Modulator source input.
RC4/C2OUT/SRNQ/P1B/TX(1)/ CK(1)/MDOUT	RC4	TTL	CMOS	General purpose I/O.
	C2OUT	—	CMOS	Comparator C2 output.
	SRNQ	—	CMOS	SR latch inverting output.
	P1B	—	CMOS	PWM output.
	TX	—	CMOS	USART asynchronous transmit.
	CK	ST	CMOS	USART synchronous clock.
	MDOUT	—	CMOS	Modulator output.
RC5/P1A/CCP1/RX(1)/DT(1)/ MDCIN2	RC5	TTL	CMOS	General purpose I/O.
	P1A	—	CMOS	PWM output.
	CCP1	ST	CMOS	Capture/Compare/PWM1.
	RX	ST	—	USART asynchronous input.
	DT	ST	CMOS	USART synchronous data.
	MDCIN2	ST	—	Modulator Carrier Input 2.
RC6/AN8/CPS8/CCP4/$\overline{SS}$	RC6	TTL	CMOS	General purpose I/O.
	AN8	AN	—	A/D Channel 8 input.
	CPS8	AN	—	Capacitive sensing input 8.
	CCP4	AN	—	Capture/Compare/PWM4.
	$\overline{SS}$	ST	—	Slave Select input.
RC7/AN9/CPS9/SDO	RC7	TTL	CMOS	General purpose I/O.
	AN9	AN	—	A/D Channel 9 input.
	CPS9	AN	—	Capacitive sensing input 9.
	SDO	—	CMOS	SPI data output.
V_{DD}	V_{DD}	Power	—	Positive supply.
V_{SS}	V_{SS}	Power	—	Ground reference.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open Drain; TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C™ = Schmitt Trigger input with I^2C levels; HV = High Voltage; XTAL = Crystal

Note 1: Pin functions can be moved using the APFCONO and APFCON1 registers (Register 12-1 and Register 12-2).

2: Default function location.

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3.1.1.2 Indirect Read with FSR

The program memory can be accessed as data by setting bit 7 of the FSRxH register and reading the matching INDFx register. The `MOVIW` instruction will place the lower eight bits of the addressed word in the W register. Writes to the program memory cannot be performed via the INDF registers. Instructions that access the program memory via the FSR require one extra instruction cycle to complete. Example 3-2 demonstrates accessing the program memory via an FSR.

The High directive will set bit<7> if a label points to a location in program memory.

EXAMPLE 3-2: ACCESSING PROGRAM MEMORY VIA FSR

```
constants
    RETLW DATA0         ;Index0 data
    RETLW DATA1         ;Index1 data
    RETLW DATA2
    RETLW DATA3
my_function
    ;… LOTS OF CODE…
    MOVLW   LOW constants
    MOVWF   FSR1L
    MOVLW   HIGH constants
    MOVWF   FSR1H
    MOVIW   0[FSR1]
;THE PROGRAM MEMORY IS IN W
```

3.2 Data Memory Organization

The data memory is partitioned in 32 memory banks with 128 bytes in a bank. Each bank consists of (Figure 3-2):

- 12 core registers
- 20 Special Function Registers (SFR)
- Up to 80 bytes of General Purpose RAM (GPR)
- 16 bytes of common RAM

The active bank is selected by writing the bank number into the Bank Select Register (BSR). Unimplemented memory will read as '`0`'. All data memory can be accessed either directly (via instructions that use the file registers) or indirectly via the two File Select Registers (FSR). See **Section 3.5 "Indirect Addressing"** for more information.

3.2.1 CORE REGISTERS

The core registers contain the registers that directly affect the basic operation. The core registers occupy the first 12 addresses of every data memory bank (addresses x00h/x08h through x0Bh/x8Bh). These registers are listed in Table 3-2 below. For detailed information, see Table 3-3.

TABLE 3-2: CORE REGISTERS

Addresses	BANKx
x00h or x80h	INDF0
x01h or x81h	INDF1
x02h or x82h	PCL
x03h or x83h	STATUS
x04h or x84h	FSR0L
x05h or x85h	FSR0H
x06h or x86h	FSR1L
x07h or x87h	FSR1H
x08h or x88h	BSR
x09h or x89h	WREG
x0Ah or x8Ah	PCLATH
x0Bh or x8Bh	INTCON

TABLE 3-9: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 6											
300h(1)	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
301h(1)	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
302h(1)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
303h(1)	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
304h(1)	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
305h(1)	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
306h(1)	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
307h(1)	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
308h(1)	BSR	—	—	—	BSR<4:0>					---0 0000	---0 0000
309h(1)	WREG	Working Register								0000 0000	uuuu uuuu
30Ah(1)	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
30Bh(1)	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 000x	0000 000u
30Ch	—	Unimplemented								—	—
30Dh	—	Unimplemented								—	—
30Eh	—	Unimplemented								—	—
30Fh	—	Unimplemented								—	—
310h	—	Unimplemented								—	—
311h	CCPR3L	Capture/Compare/PWM Register 3 (LSB)								xxxx xxxx	uuuu uuuu
312h	CCPR3H	Capture/Compare/PWM Register 3 (MSB)								xxxx xxxx	uuuu uuuu
313h	CCP3CON	—	—	DC3B<1:0>		CCP3M<3:0>				--00 0000	--00 0000
314h	—	Unimplemented								—	—
315h	—	Unimplemented								—	—
316h	—	Unimplemented								—	—
317h	—	Unimplemented								—	—
318h	CCPR4L	Capture/Compare/PWM Register 4 (LSB)								xxxx xxxx	uuuu uuuu
319h	CCPR4H	Capture/Compare/PWM Register 4 (MSB)								xxxx xxxx	uuuu uuuu
31Ah	CCP4CON	—	—	DC4B<1:0>		CCP4M<3:0>				--00 0000	--00 0000
31Bh	—	Unimplemented								—	—
31Ch	—	Unimplemented								—	—
31Dh	—	Unimplemented								—	—
31Eh	—	Unimplemented								—	—
31Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, r = reserved.
Shaded locations are unimplemented, read as '0'.

Note 1: These registers can be addressed from any bank.
2: PIC16(L)F1828 only.
3: PIC16(L)F1824 only.
4: Unimplemented, read as '1'.

REGISTER 4-1: CONFIGURATION WORD 1 (CONTINUED)

bit 2-0 **FOSC<2:0>:** Oscillator Selection bits

`111` = ECH: External Clock, High-Power mode (4-32 MHz): device clock supplied to CLKIN pin
`110` = ECM: External Clock, Medium-Power mode (0.5-4 MHz): device clock supplied to CLKIN pin
`101` = ECL: External Clock, Low-Power mode (0-0.5 MHz): device clock supplied to CLKIN pin
`100` = INTOSC oscillator: I/O function on CLKIN pin
`011` = EXTRC oscillator: External RC circuit connected to CLKIN pin
`010` = HS oscillator: High-speed crystal/resonator connected between OSC1 and OSC2 pins
`001` = XT oscillator: Crystal/resonator connected between OSC1 and OSC2 pins
`000` = LP oscillator: Low-power crystal connected between OSC1 and OSC2 pins

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.
2: The entire data EEPROM will be erased when the code protection is turned off during an erase.
3: The entire program memory will be erased when the code protection is turned off.

9.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a SLEEP instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{PD}$ bit of the STATUS register is cleared.
3. $\overline{TO}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before SLEEP was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Timer1 oscillator

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on these modules.

9.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{MCLR}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 7.10 "Determining the Cause of a Reset"**.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is enabled, the device executes the instruction after the SLEEP instruction, the device will call the Interrupt Service Routine. In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

9.1.1 WAKE-UP USING INTERRUPTS

When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction
  - SLEEP instruction will execute as a NOP
  - WDT and WDT prescaler will not be cleared
  - $\overline{TO}$ bit of the STATUS register will not be set
  - $\overline{PD}$ bit of the STATUS register will not be cleared
- If the interrupt occurs **during or after** the execution of a SLEEP instruction
  - SLEEP instruction will be completely executed
  - Device will immediately wake-up from Sleep
  - WDT and WDT prescaler will be cleared
  - $\overline{TO}$ bit of the STATUS register will be set
  - $\overline{PD}$ bit of the STATUS register will be cleared

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REGISTER 12-12: ANSELB: PORTB ANALOG SELECT REGISTER

U-0	U-0	R/W-1/1	R/W-1/1	U-0	U-0	U-0	U-0
—	—	ANSB5	ANSB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-4 **ANSB<5:4>**: Analog Select between Analog or Digital Function on pins RB<5:4>, respectively
0 = Digital I/O. Pin is assigned to port or digital special function.
1 = Analog input. Pin is assigned as analog input[1]. Digital input buffer disabled.

bit 3-0 **Unimplemented:** Read as ‘0’

Note 1: When setting a pin to an analog input, the corresponding TRIS bit must be set to Input mode in order to allow external control of the voltage on the pin.

REGISTER 12-13: WPUB: WEAK PULL-UP PORTB REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	U-0	U-0	U-0	U-0
WPUB7	WPUB6	WPUB5	WPUB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **WPUB<7:4>**: Weak Pull-up Register bits[1,2]
1 = Pull-up enabled
0 = Pull-up disabled

bit 3-0 **Unimplemented:** Read as ‘0’

Note 1: Global $\overline{\text{WPUEN}}$ bit of the OPTION_REG register must be cleared for individual pull-ups to be enabled.
2: The weak pull-up device is automatically disabled if the pin is in configured as an output.

REGISTER 12-14: INLVLB: PORTB INPUT LEVEL CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	U-0	U-0	U-0
INLVLB7	INLVLB6	INLVLB5	INLVLB4	—	—	—	—
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-4 **INLVLB<7:4>:** PORTB Input Level Select bits
For RB<7:4> pins, respectively
1 = ST input used for PORT reads and interrupt-on-change
0 = TTL input used for PORT reads and interrupt-on-change

bit 3-0 **Unimplemented:** Read as ‘0

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15.0 TEMPERATURE INDICATOR MODULE

This family of devices is equipped with a temperature circuit designed to measure the operating temperature of the silicon die. The circuit's range of operating temperature falls between of -40°C and +85°C. The output is a voltage that is proportional to the device temperature. The output of the temperature indicator is internally connected to the device ADC.

The circuit may be used as a temperature threshold detector or a more accurate temperature indicator, depending on the level of calibration performed. A one-point calibration allows the circuit to indicate a temperature closely surrounding that point. A two-point calibration allows the circuit to sense the entire range of temperature more accurately. Reference Application Note AN1333, "*Use and Calibration of the Internal Temperature Indicator*" (DS01333) for more details regarding the calibration process.

15.1 Circuit Operation

Figure 15-1 shows a simplified block diagram of the temperature circuit. The proportional voltage output is achieved by measuring the forward voltage drop across multiple silicon junctions.

Equation 15-1 describes the output characteristics of the temperature indicator.

EQUATION 15-1: VOUT RANGES

High Range: $V_{OUT} = V_{DD} - 4V_T$

Low Range: $V_{OUT} = V_{DD} - 2V_T$

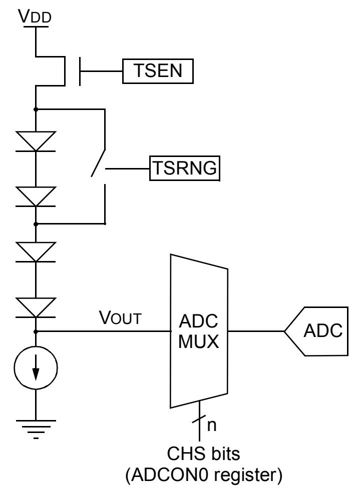
The temperature sense circuit is integrated with the Fixed Voltage Reference (FVR) module. See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information.

The circuit is enabled by setting the TSEN bit of the FVRCON register (Register 14-1). When disabled, the circuit draws no current.

The circuit operates in either high or low range. The high range, selected by setting the TSRNG bit of the FVRCON register, provides a wider output voltage. This provides more resolution over the temperature range, but may be less consistent from part to part. This range requires a higher bias voltage to operate and thus, a higher VDD is needed.

The low range is selected by clearing the TSRNG bit of the FVRCON register. The low range generates a lower voltage drop and thus, a lower bias voltage is needed to operate the circuit. The low range is provided for low voltage operation.

FIGURE 15-1: TEMPERATURE CIRCUIT DIAGRAM



15.2 Minimum Operating VDD vs. Minimum Sensing Temperature

When the temperature circuit is operated in low range, the device may be operated at any operating voltage that is within specifications.

When the temperature circuit is operated in high range, the device operating voltage, VDD, must be high enough to ensure that the temperature circuit is correctly biased.

Table 15-1 shows the recommended minimum VDD vs. range setting.

TABLE 15-1: RECOMMENDED VDD VS. RANGE

Min. VDD, TSRNG = 1	Min. VDD, TSRNG = 0
3.6V	1.8V

15.3 Temperature Output

The output of the circuit is measured using the internal analog-to-digital converter. A channel is reserved for the temperature circuit output. Refer to **Section 16.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

15.4 ADC Acquisition Time

To ensure accurate temperature measurements, the user must wait at least 200 μs after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 μs between sequential conversions of the temperature indicator output.

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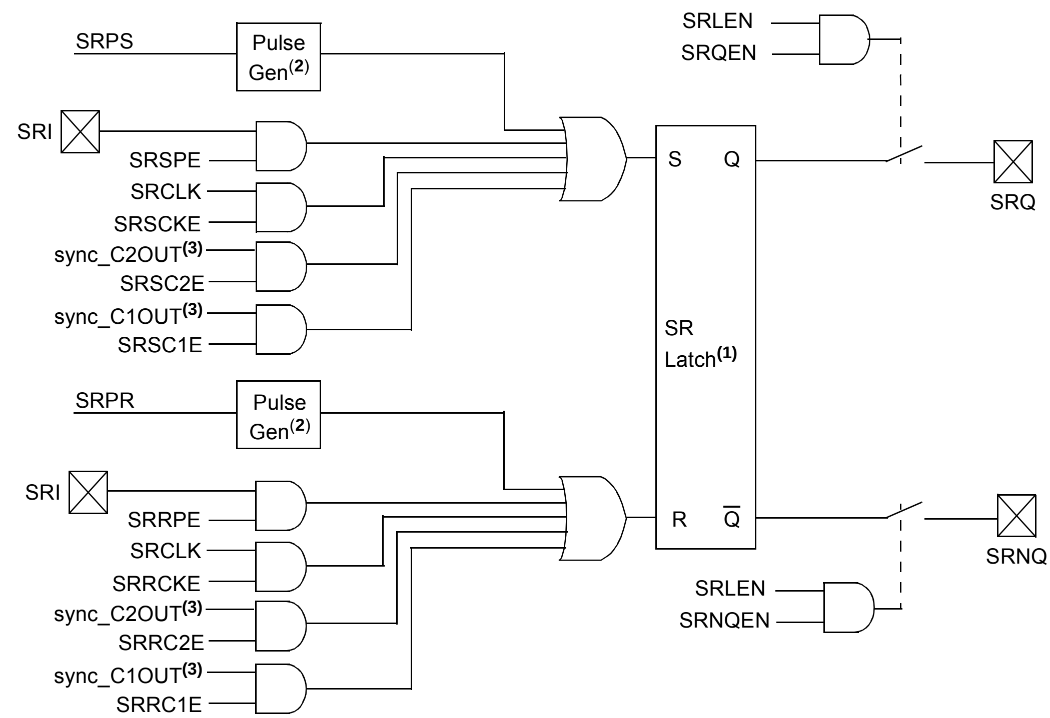
FIGURE 18-1: SR LATCH SIMPLIFIED BLOCK DIAGRAM



Note 1: If R = `1` and S = `1` simultaneously, Q = `0`, $\overline{Q}$ = `1`

2: Pulse generator causes a 1 Q-state pulse width.

3: Name denotes the connection point at the comparator output.

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22.0 TIMER2/4/6 MODULES

There are up to three identical Timer2-type modules available. To maintain pre-existing naming conventions, the Timers are called Timer2, Timer4 and Timer6 (also Timer2/4/6).

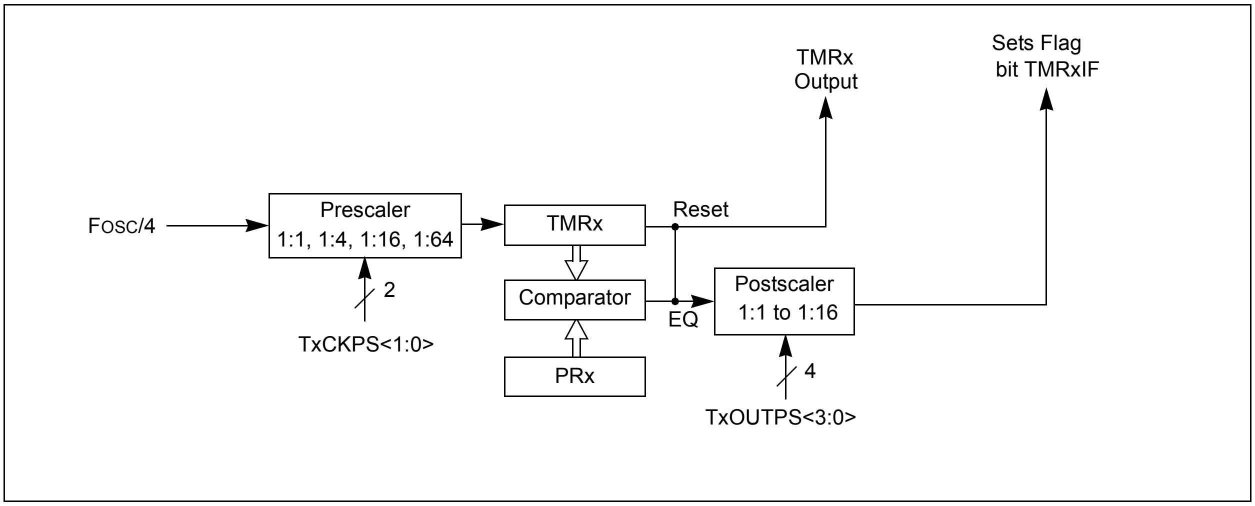
Note:	The 'x' variable used in this section is used to designate Timer2, Timer4, or Timer6. For example, TxCON references T2CON, T4CON, or T6CON. PRx references PR2, PR4, or PR6.

The Timer2/4/6 modules incorporate the following features:

- 8-bit Timer and Period registers (TMRx and PRx, respectively)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4, 1:16, and 1:64)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMRx match with PRx, respectively
- Optional use as the shift clock for the MSSPx modules (Timer2 only)

See Figure 22-1 for a block diagram of Timer2/4/6.

FIGURE 22-1: TIMER2/4/6 BLOCK DIAGRAM



24.1.5 CAPTURE DURING SLEEP

Capture mode depends upon the Timer1 module for proper operation. There are two options for driving the Timer1 module in Capture mode. It can be driven by the instruction clock (FOSC/4), or by an external clock source.

When Timer1 is clocked by FOSC/4, Timer1 will not increment during Sleep. When the device wakes from Sleep, Timer1 will continue from its previous state.

Capture mode will operate during Sleep when Timer1 is clocked by an external clock source.

24.1.6 ALTERNATE PIN LOCATIONS

This module incorporates I/O pins that can be moved to other locations with the use of the alternate pin function registers, APFCON0 and APFCON1. To determine which pins can be moved and what their default locations are upon a Reset, see **Section 12.1 “Alternate Pin Function”** for more information.

TABLE 24-2: SUMMARY OF REGISTERS ASSOCIATED WITH CAPTURE

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON1	—	—	—	—	P1DSEL	P1CSEL	P2BSEL	CCP2SEL	118
CCPxCON	PxM<1:0>(1)		DCxB<1:0>		CCPxM<3:0>				225
CCPRxL	Capture/Compare/PWM Register x Low Byte (LSB)								203*
CCPRxH	Capture/Compare/PWM Register x High Byte (MSB)								203*
CMxCON0	CxON	CxOUT	CxOE	CxPOL	—	CxSP	CxHYS	CxSYNC	171
CMxCON1	CxINTP	CxINTN	CxPCH<1:0>		—	—	CxNCH<1:0>		172
INLVLA	—	—	INLVLA5	INLVLA4	INLVLA3	INLVLA2	INLVLA1	INLVLA0	123
INLVLC	INLVLC7(2)	INLVLC6(2)	INLVLC5	INLVLC4	INLVLC3	INLVLC2	INLVLC1	INLVLC0	134
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	89
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	90
PIE2	OSFIE	C2IE	C1IE	EEIE	BCL1IE	—	—	CCP2IE	91
PIE3	—	—	CCP4IE	CCP3IE	TMR6IE	—	TMR4IE	—	92
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	93
PIR2	OSFIF	C2IF	C1IF	EEIF	BCL1IF	—	—	CCP2IF	94
PIR3	—	—	CCP4IF	CCP3IF	TMR6IF	—	TMR4IF	—	95
T1CON	TMR1CS1	TMR1CS0	T1CKPS1	T1CKPS0	T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	186
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	T1GGO/DONE	T1GVAL	T1GSS1	T1GSS0	187
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								182*
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								182*
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	121
TRISC	TRISC7(2)	TRISC6(2)	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	132

Legend: — = unimplemented locations, read as ‘0’. Shaded cells are not used by the Capture.
* Page provides register information.

Note 1: Applies to ECCP modules only.
2: PIC16(L)F1828 only.

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FIGURE 25-36: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

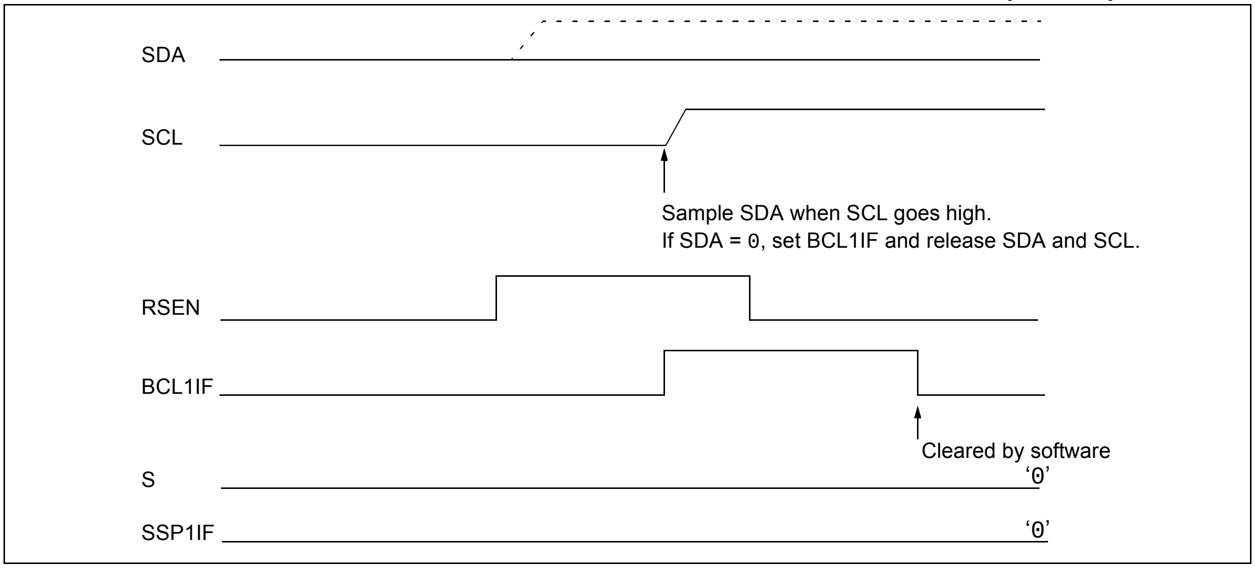
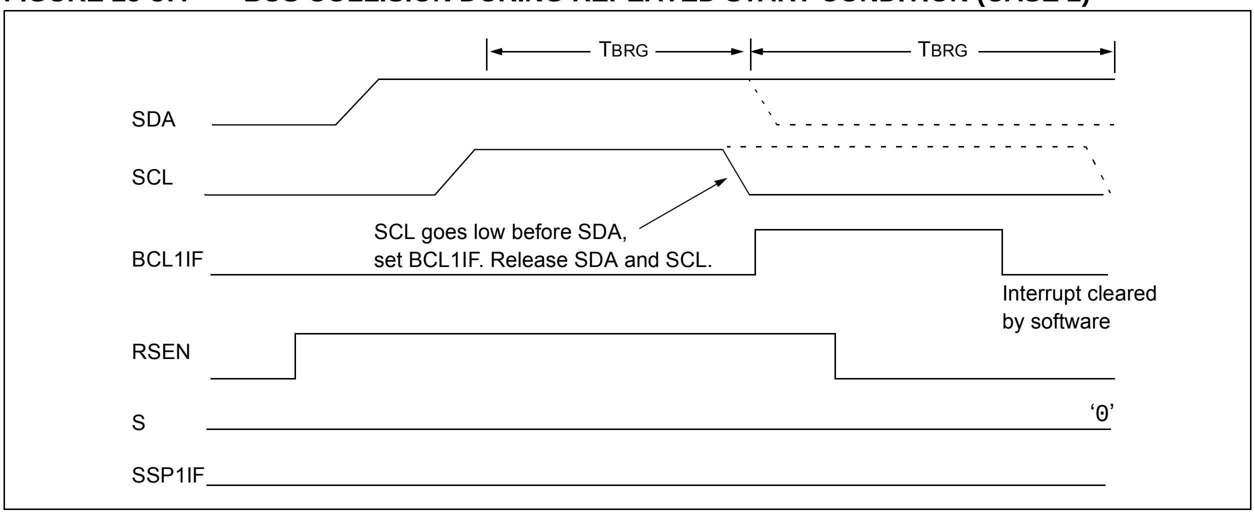


FIGURE 25-37: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



26.1.2.8 Asynchronous Reception Setup:

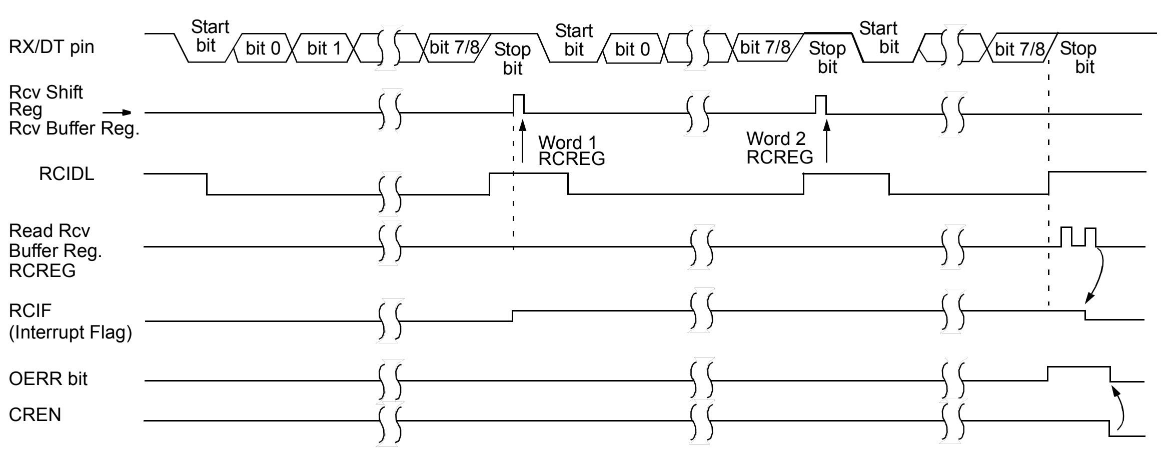
1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 26.3 "EUSART Baud Rate Generator (BRG)"**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. If 9-bit reception is desired, set the RX9 bit.
6. Enable reception by setting the CREN bit.
7. The RCIF interrupt flag bit will be set when a character is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
8. Read the RCSTA register to get the error flags and, if 9-bit data reception is enabled, the ninth data bit.
9. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register.
10. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.

26.1.2.9 9-bit Address Detection Mode Setup

This mode would typically be used in RS-485 systems. To set up an Asynchronous Reception with Address Detect Enable:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 26.3 "EUSART Baud Rate Generator (BRG)"**).
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the serial port by setting the SPEN bit. The SYNC bit must be clear for asynchronous operation.
4. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
5. Enable 9-bit reception by setting the RX9 bit.
6. Enable address detection by setting the ADDEN bit.
7. Enable reception by setting the CREN bit.
8. The RCIF interrupt flag bit will be set when a character with the ninth bit set is transferred from the RSR to the receive buffer. An interrupt will be generated if the RCIE interrupt enable bit was also set.
9. Read the RCSTA register to get the error flags. The ninth data bit will always be set.
10. Get the received eight Least Significant data bits from the receive buffer by reading the RCREG register. Software determines if this is the device's address.
11. If an overrun occurred, clear the OERR flag by clearing the CREN receiver enable bit.
12. If the device has been addressed, clear the ADDEN bit to allow all received data into the receive buffer and generate interrupts.

FIGURE 26-5: ASYNCHRONOUS RECEPTION



Note: This timing diagram shows three words appearing on the RX input. The RCREG (receive buffer) is read after the third word, causing the OERR (overrun) bit to be set.

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TABLE 26-5: BAUD RATES FOR ASYNCHRONOUS MODES

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 32.000 MHz			Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	1221	1.73	255	1200	0.00	239	1200	0.00	143
2400	2404	0.16	207	2404	0.16	129	2400	0.00	119	2400	0.00	71
9600	9615	0.16	51	9470	-1.36	32	9600	0.00	29	9600	0.00	17
10417	10417	0.00	47	10417	0.00	29	10286	-1.26	27	10165	-2.42	16
19.2k	19.23k	0.16	25	19.53k	1.73	15	19.20k	0.00	14	19.20k	0.00	8
57.6k	55.55k	-3.55	3	—	—	—	57.60k	0.00	7	57.60k	0.00	2
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 0, BRG16 = 0											
	Fosc = 8.000 MHz			Fosc = 4.000 MHz			Fosc = 3.6864 MHz			Fosc = 1.000 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	300	0.16	207	300	0.00	191	300	0.16	51
1200	1202	0.16	103	1202	0.16	51	1200	0.00	47	1202	0.16	12
2400	2404	0.16	51	2404	0.16	25	2400	0.00	23	—	—	—
9600	9615	0.16	12	—	—	—	9600	0.00	5	—	—	—
10417	10417	0.00	11	10417	0.00	5	—	—	—	—	—	—
19.2k	—	—	—	—	—	—	19.20k	0.00	2	—	—	—
57.6k	—	—	—	—	—	—	57.60k	0.00	0	—	—	—
115.2k	—	—	—	—	—	—	—	—	—	—	—	—

BAUD RATE	SYNC = 0, BRGH = 1, BRG16 = 0											
	Fosc = 32.000 MHz			Fosc = 20.000 MHz			Fosc = 18.432 MHz			Fosc = 11.0592 MHz		
	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)	Actual Rate	% Error	SPBRG value (decimal)
300	—	—	—	—	—	—	—	—	—	—	—	—
1200	—	—	—	—	—	—	—	—	—	—	—	—
2400	—	—	—	—	—	—	—	—	—	—	—	—
9600	9615	0.16	207	9615	0.16	129	9600	0.00	119	9600	0.00	71
10417	10417	0.00	191	10417	0.00	119	10378	-0.37	110	10473	0.53	65
19.2k	19.23k	0.16	103	19.23k	0.16	64	19.20k	0.00	59	19.20k	0.00	35
57.6k	57.14k	-0.79	34	56.82k	-1.36	21	57.60k	0.00	19	57.60k	0.00	11
115.2k	117.64k	2.12	16	113.64k	-1.36	10	115.2k	0.00	9	115.2k	0.00	5

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CALL	Call Subroutine
Syntax:	[*label*] CALL k
Operands:	$0 \leq k \leq 2047$
Operation:	(PC)+ 1→ TOS, k → PC<10:0>, (PCLATH<4:3>) → PC<12:11>
Status Affected:	None
Description:	Call Subroutine. First, return address (PC + 1) is pushed onto the stack. The 11-bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a 2-cycle instruction.

CALLW	Subroutine Call With W
Syntax:	[*label*] CALLW
Operands:	None
Operation:	(PC) +1 → TOS, (W) → PC<7:0>, (PCLATH<6:0>) → PC<14:8>
Status Affected:	None
Description:	Subroutine call with W. First, the return address (PC + 1) is pushed onto the return stack. Then, the contents of W is loaded into PC<7:0>, and the contents of PCLATH into PC<14:8>. CALLW is a 2-cycle instruction.

CLRF	Clear f
Syntax:	[*label*] CLRF f
Operands:	$0 \leq f \leq 127$
Operation:	00h → (f) 1 → Z
Status Affected:	Z
Description:	The contents of register ‘f’ are cleared and the Z bit is set.

CLRW	Clear W
Syntax:	[*label*] CLRW
Operands:	None
Operation:	00h → (W) 1 → Z
Status Affected:	Z
Description:	W register is cleared. Zero bit (Z) is set.

CLRWDT	Clear Watchdog Timer
Syntax:	[*label*] CLRWDT
Operands:	None
Operation:	00h → WDT 0 → WDT prescaler, 1 → $\overline{TO}$ 1 → $\overline{PD}$
Status Affected:	$\overline{TO}$, $\overline{PD}$
Description:	CLRWDT instruction resets the Watchdog Timer. It also resets the prescaler of the WDT. Status bits $\overline{TO}$ and $\overline{PD}$ are set.

COMF	Complement f
Syntax:	[*label*] COMF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	$(\overline{f})$ → (destination)
Status Affected:	Z
Description:	The contents of register ‘f’ are complemented. If ‘d’ is ‘0’, the result is stored in W. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

DECF	Decrement f
Syntax:	[*label*] DECF f,d
Operands:	$0 \leq f \leq 127$ $d \in [0,1]$
Operation:	(f) - 1 → (destination)
Status Affected:	Z
Description:	Decrement register ‘f’. If ‘d’ is ‘0’, the result is stored in the W register. If ‘d’ is ‘1’, the result is stored back in register ‘f’.

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30.6 Thermal Considerations

Standard Operating Conditions (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +125°C					
Param No.	**Sym.**	**Characteristic**	**Typ.**	**Units**	**Conditions**
TH01	θ_{JA}	Thermal Resistance Junction to Ambient	70.0	°C/W	14-pin PDIP package
			95.3	°C/W	14-pin SOIC package
			100.0	°C/W	14-pin TSSOP package
			45.7	°C/W	16-pin QFN (4x4mm) package
			31.8	°C/W	16-pin UQFN (4x4mm) package
			62.2	°C/W	20-pin PDIP package
			77.7	°C/W	20-pin SOIC package
			87.3	°C/W	20-pin SSOP package
			43.0	°C/W	20-pin QFN (4x4mm) package
			32.8	°C/W	20-pin UQFN (4x4mm) package
TH02	θ_{JC}	Thermal Resistance Junction to Case	32.8	°C/W	14-pin PDIP package
			31.0	°C/W	14-pin SOIC package
			24.4	°C/W	14-pin TSSOP package
			6.3	°C/W	16-pin QFN (4x4mm) package
			24.4	°C/W	16-pin UQFN (4x4mm) package
			27.5	°C/W	20-pin PDIP package
			23.1	°C/W	20-pin SOIC package
			31.1	°C/W	20-pin SSOP package
			5.3	°C/W	20-pin QFN (4x4mm) package
			27.4	°C/W	20-pin UQFN (4x4mm) package
TH03	T_{JMAX}	Maximum Junction Temperature	150	°C	
TH04	PD	Power Dissipation	—	W	PD = $P_{INTERNAL}$ + $P_{I/O}$
TH05	$P_{INTERNAL}$	Internal Power Dissipation	—	W	$P_{INTERNAL}$ = I_{DD} x V_{DD} **(Note 1)**
TH06	$P_{I/O}$	I/O Power Dissipation	—	W	$P_{I/O} = \Sigma (I_{OL} * V_{OL}) + \Sigma (I_{OH} * (V_{DD} - V_{OH}))$
TH07	P_{DER}	Derated Power	—	W	$P_{DER} = PD_{MAX} (T_J - T_A)/\theta_{JA}$ **(Note 2)**

Note 1: I_{DD} is current to run the chip alone without driving any load on the output pins.
2: T_A = Ambient Temperature, T_J = Junction Temperature

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TABLE 30-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	MCLR Pulse Width (low)	2	—	—	μs	
31	TWDTLP	Watchdog Timer Time-out Period (No Prescaler)	12	16	20	ms	VDD = 3.3V-5V
32	TOST	Oscillator Start-up Timer Period(1)	—	1024	—	Tosc	
33*	TPWRT	Power-up Timer Period, PWRTE = 0	40	65	140	ms	
34*	TIOZ	I/O high-impedance from MCLR Low or Watchdog Timer Reset	—	—	2.0	μs	
35	VBOR	Brown-out Reset Voltage(2)	2.55 1.80	2.70 1.9	2.85 2.05	V V	BORV = 0 BORV = 1
36*	VHYST	Brown-out Reset Hysteresis	20	35	75	mV	-40°C to +85°C
37*	TBORDC	Brown-out Reset DC Response Time	0	1	35	μs	VDD ≤ VBOR

* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: By design, the Oscillator Start-up (OST) counts the first 1.024 cycles, independent of frequency.

2: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

FIGURE 30-10: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

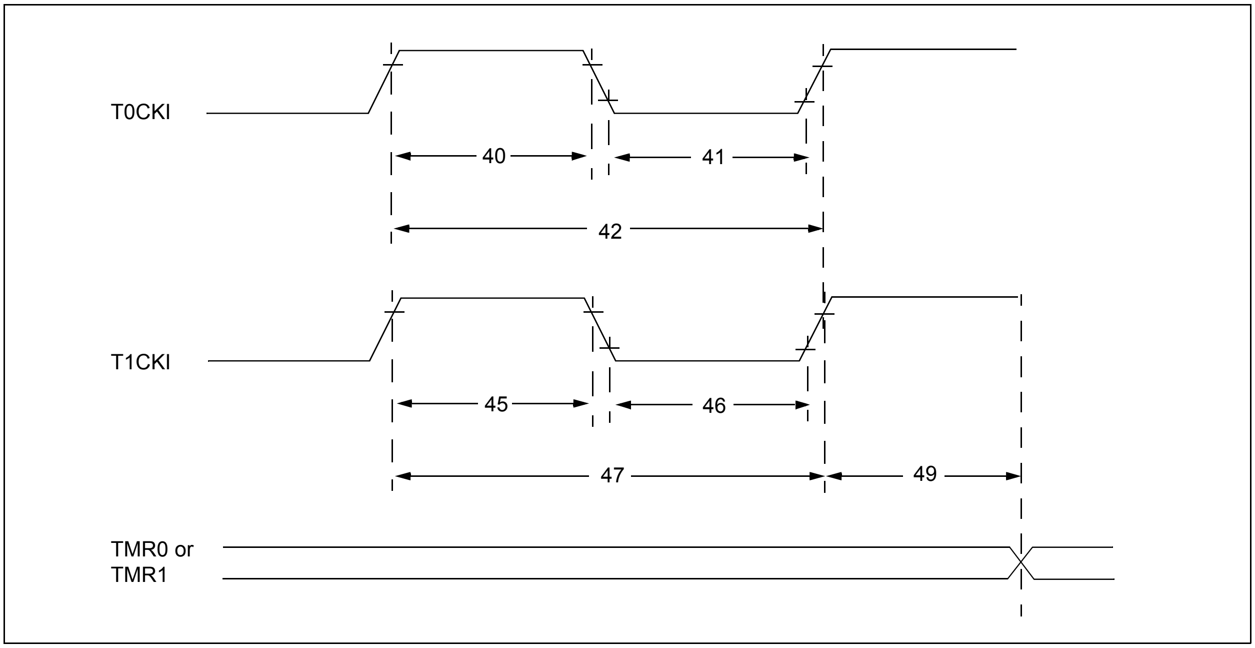


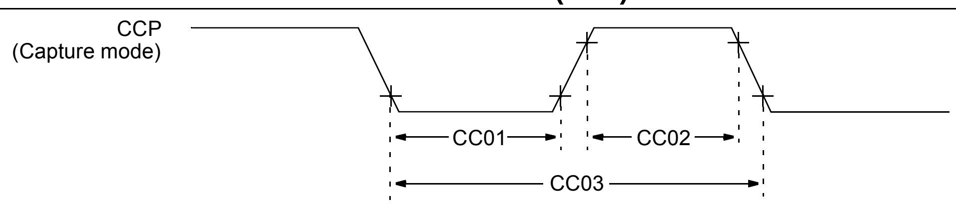
TABLE 30-6: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Standard Operating Conditions (unless otherwise stated)
Operating Temperature -40°C ≤ TA ≤ +125°C

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
40*	TT0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	TT0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	TT0P	T0CKI Period		Greater of: 20 or $\frac{TCY + 40}{N}$	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	TT1H	T1CKI High Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	TT1L	T1CKI Low Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	TT1P	T1CKI Input Period	Synchronous	Greater of: 30 or $\frac{TCY + 40}{N}$	—	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	60	—	—	ns	
48	FT1	Timer1 Oscillator Input Frequency Range (oscillator enabled by setting bit T1OSCEN)		32.4	32.768	33.1	kHz	
49*	TCKEZTMR1	Delay from External Clock Edge to Timer Increment		2 TOSC	—	7 TOSC	—	Timers in Sync mode

* These parameters are characterized but not tested.
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 30-11: CAPTURE/COMPARE/PWM TIMINGS (CCP)



Note: Refer to Figure 30.5 for load conditions.

TABLE 30-7: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP)

Standard Operating Conditions (unless otherwise stated)
Operating Temperature -40°C ≤ TA ≤ +125°C

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
CC01*	TccL	CCP Input Low Time	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	20	—	—	ns	
CC02*	TccH	CCP Input High Time	No Prescaler	0.5TCY + 20	—	—	ns	
			With Prescaler	20	—	—	ns	
CC03*	TccP	CCP Input Period		$\frac{3TCY + 40}{N}$	—	—	ns	N = prescale value

* These parameters are characterized but not tested.
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 31-15: IDD TYPICAL, HFINTOSC MODE, PIC16LF1824/8 ONLY

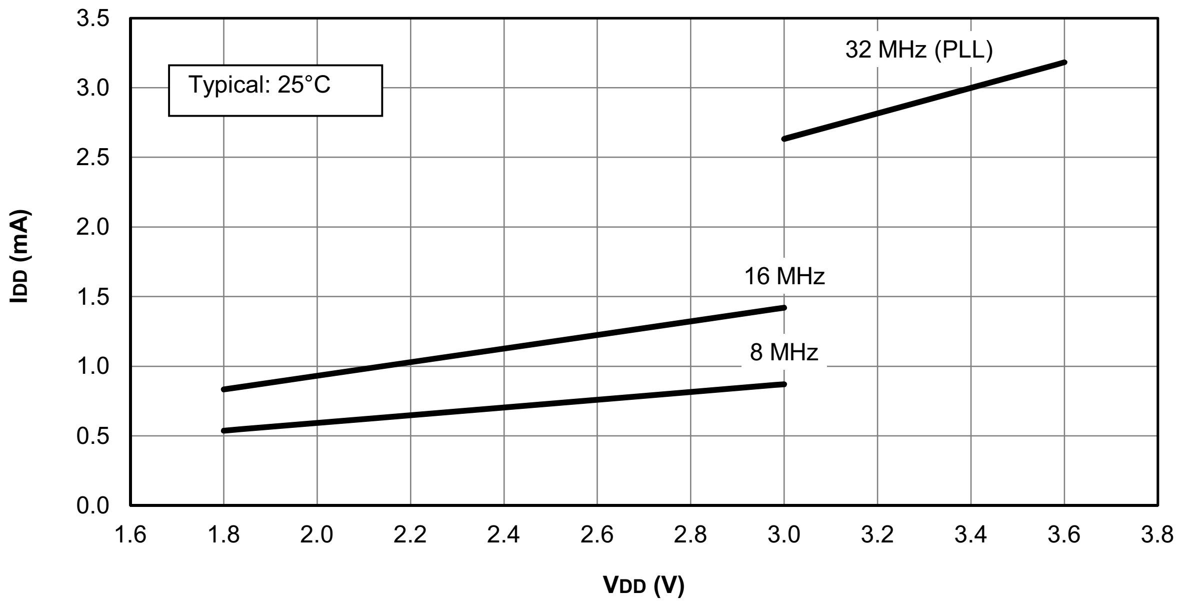

FIGURE 31-16: IDD MAXIMUM, HFINTOSC MODE, PIC16LF1824/8 ONLY

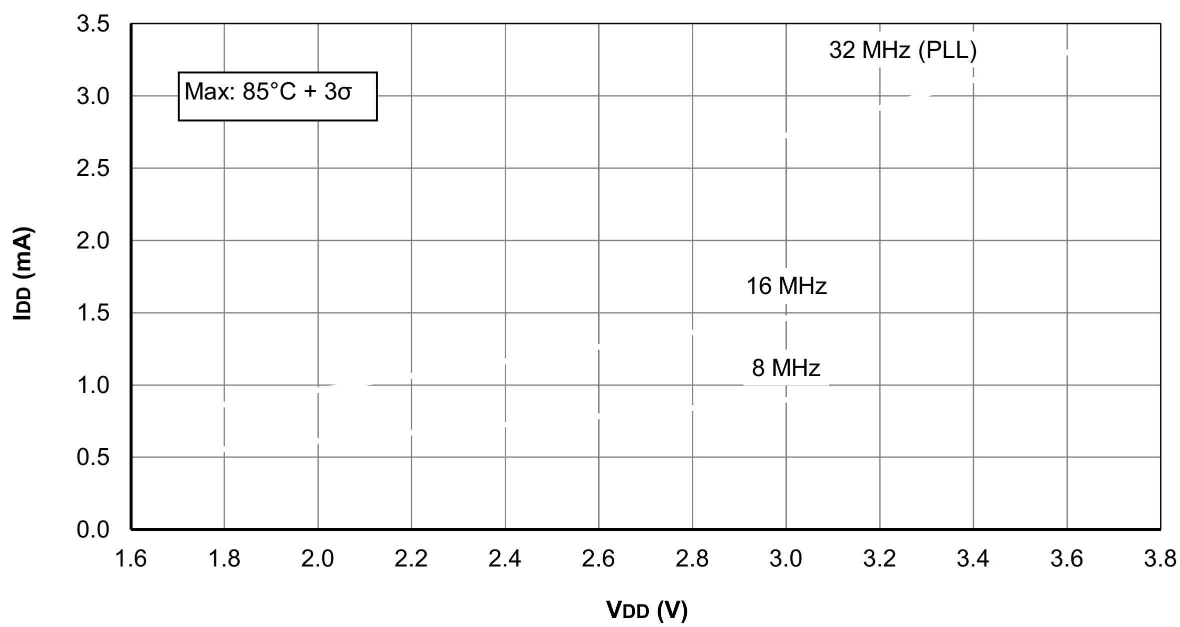

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FIGURE 31-56: COMPARATOR RESPONSE TIME, NORMAL-POWER MODE (CxSP = 1)

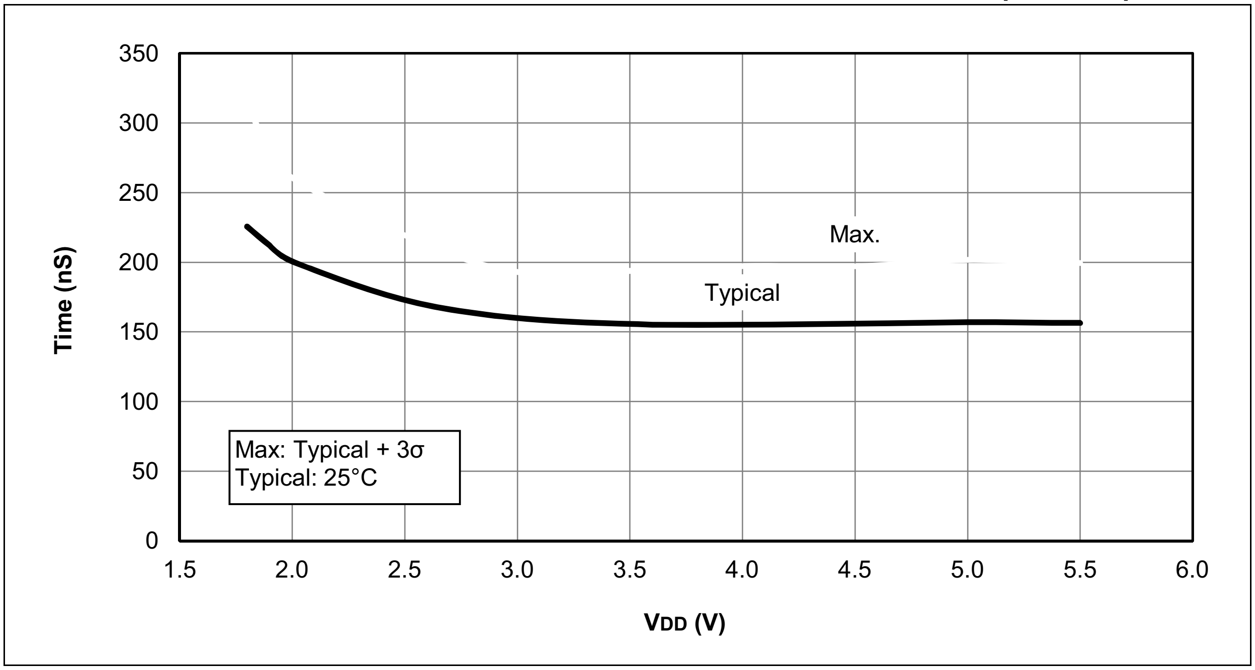
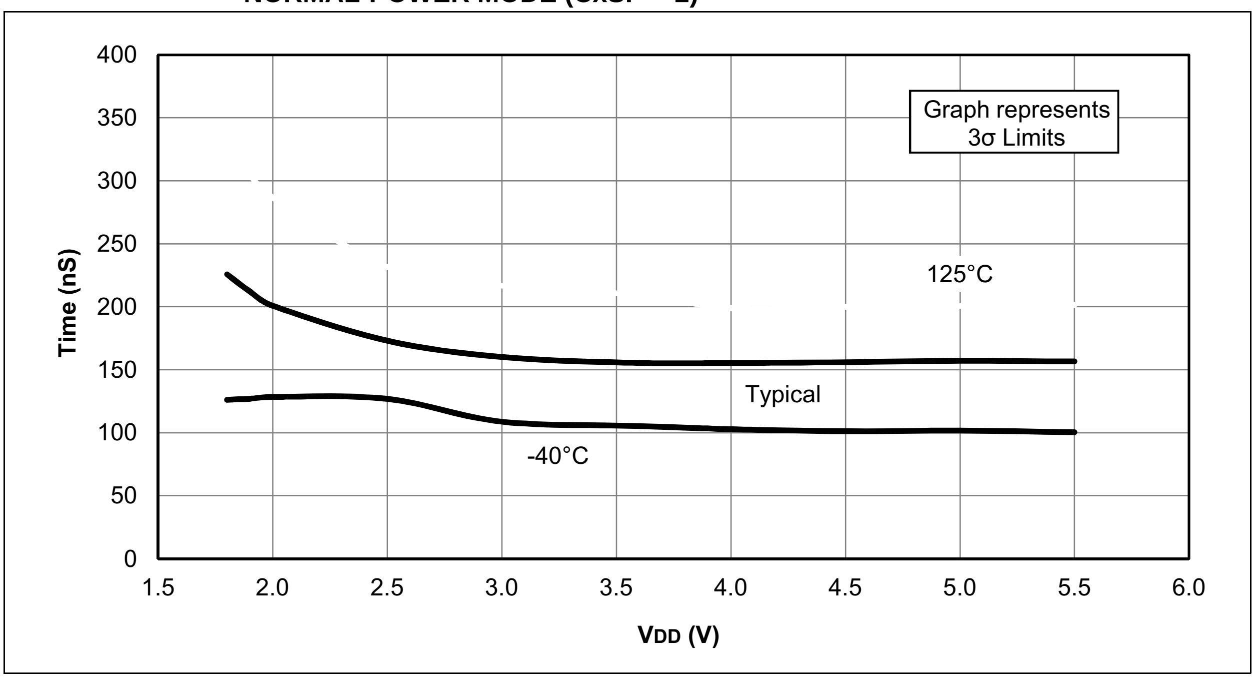


FIGURE 31-57: COMPARATOR RESPONSE TIME OVER TEMPERATURE, NORMAL-POWER MODE (CxSP = 1)



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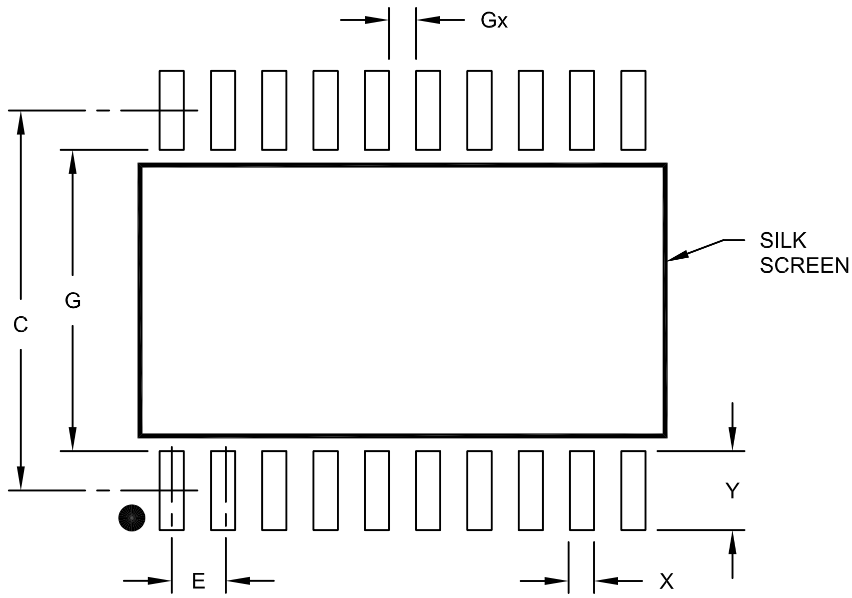
20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X20)	X			0.60
Contact Pad Length (X20)	Y			1.95
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.45		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2094A

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